

The direct determination of MOSFET parameters from the I_D versus V_S curve at low V_{DS}

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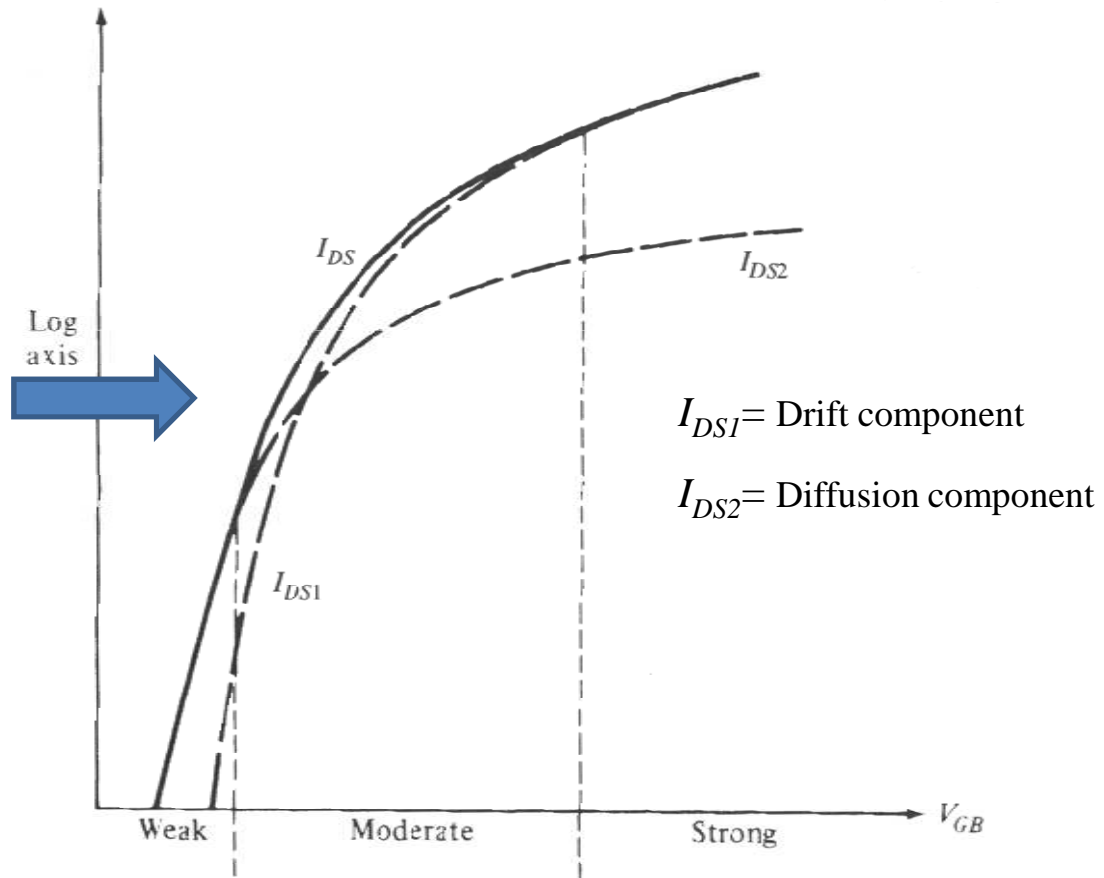
Contents

- 1** - Threshold Voltage definitions
- 2** - Determination of MOSFET parameters from $I_D \times V_S$ curve, (channel_conductance)/ I_d method
- 3** - Comparison with g_m/I_d method
- 4** - Applications of the threshold voltage determinations
- 5** - Conclusions

Threshold voltage (V_T)

Near the threshold condition (moderate inversion), both the drift and diffusion transport mechanisms are important.

No critical point can be directly identified



* from Yannis Tsvividis, Operation and Modeling of The MOS transistor, MCGraw-Hill

Classical threshold voltage (V_T) definition

Classical (surface potential based) definition of threshold:

$$\phi_S = 2\phi_F + V_C$$

Where : ϕ_S - surface potential for $V_G = V_T$
 ϕ_F - Fermi potential in the substrate
 V_C - channel potential

In principle the direct determination of the threshold voltage is possible

- 1) calculate the saturation drain current I_{DTh} for $\phi_S = 2\phi_F + V_C$
- 2) inject I_{DTh} in the transistor and measure $V_G = V_T$

Drawbacks

- geometrical (W, L) and technological parameters (mobility, oxide thickness,..) are needed to calculate I_{DTh}
- the transistor operates in the saturation region where several secondary effects are relevant

Current based threshold definition

$$V_T = V_G, \text{ when } I_{drift} = I_{diff}$$

For a MOSFET the current defined threshold corresponds to an inversion charge density equal to the thermal charge density (the effective channel capacitance per unit area times the thermal voltage).

For a bulk MOSFET

$$Q'_I = -nC'_{ox} \phi_t$$

where n is the slope factor

Relationship between threshold voltages

Threshold Definition	Physical Meaning	Value of ϕ_S at threshold	Value of Q'_I at threshold	Difference in V_{T0} relative to classical definition
$\phi_S = 2\phi_F + V_C$	Surface concentration of electrons = bulk concentration of holes	$2\phi_F + V_C$	$-(n-1)C'_{ox}\phi_t$	0
$Q'_I = -nC'_{ox}\phi_t$	50% drop (relative to the peak) in the g_m/I_D curve	$2\phi_F + V_C + \phi_t \ln\left(\frac{n}{n-1}\right)$	$-nC'_{ox}\phi_t$	$\phi_t \left[1 + n \ln\left(\frac{n}{n-1}\right) \right]$

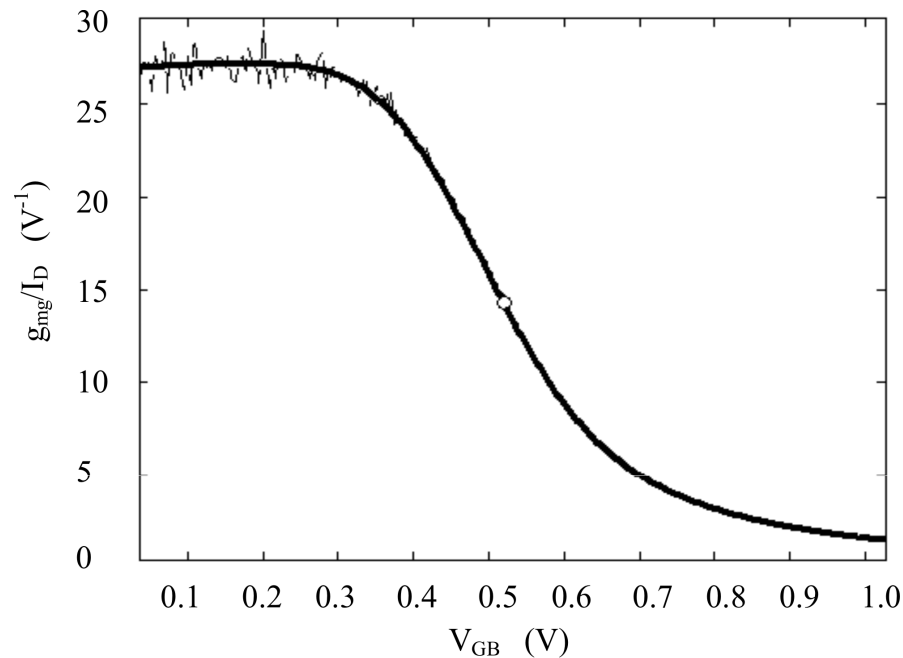
'Ideal' threshold voltage extraction procedure

- No parameters are needed to calculate the threshold current
- The transistor operates at low current levels and in the linear region to minimize series resistances and short channel effects



gm/Id curve in the linear region

VT determination from gm/Id curve in the linear region



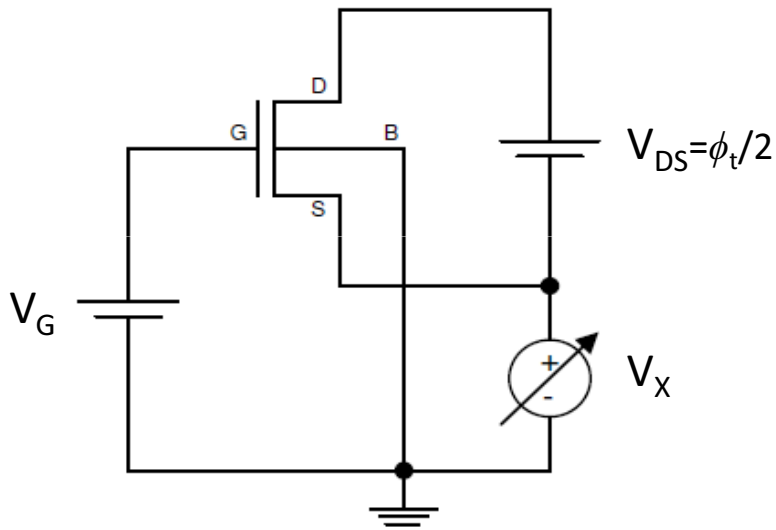
- Transconductance-to-current ratio for $V_{DS} \cong \phi_t/2$ and $V_S=0$.

$$\text{Threshold } g_m/I_D \cong 0.5 (g_m/I_D)_{max}$$

Drawback $(g_m/I_D)_{max}$ has some dependence on V_G

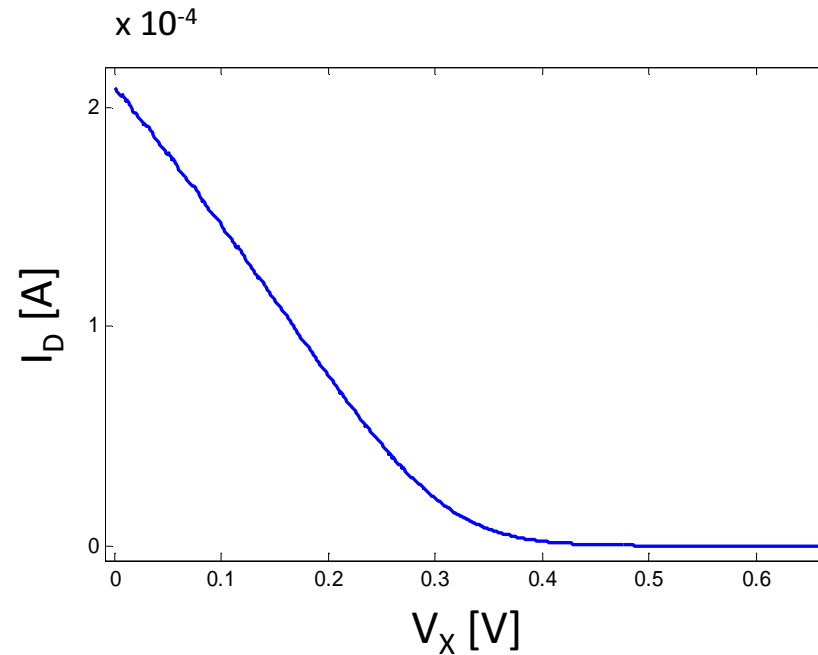
The new (channel conductance G_{no}/I_D) methodology

Direct determination of MOSFET parameters from the I_D versus V_S curve at low V_{DS}



$$\Delta V_S = \Delta V_D = \Delta V_X$$

$$\frac{\partial I_D}{\partial V_X} = -g_{ms} + g_{md} = G_{no}$$



The G_{n0}/I_d methodology

Transistor operation:

- low V_{DS}
- weak and moderate inversion
- fixed V_G

Negligible effects of :


- series resistances
- field dependent mobility
- slope factor variation
- channel length modulation



The G_{n0}/I_D methodology – extract V_T and I_S


From transistor model

$$g_{ms(d)} = \frac{2I_S}{\phi_t} (\sqrt{1+i_{f(d)}} - 1)$$

$$I_D = I_S(i_f - i_r) \quad I_S = \mu C'_{ox} n \frac{\phi_t^2 W}{2 L}$$


$$\frac{G_{n0}}{I_D} = \frac{-2}{\phi_t (\sqrt{1+i_f} + \sqrt{1+i_r})} = \left(\frac{G_{n0}}{I_D} \right)_{\min} \frac{2}{\sqrt{1+i_f} + \sqrt{1+i_r}}$$

From UICM

$$\frac{V_P - V_{S(D)}}{\phi_t} = \sqrt{1+i_{f(r)}} - 2 + \ln(\sqrt{1+i_{f(r)}} - 1)$$


When $i_f=3 \rightarrow V_P=V_S=V_X$

When

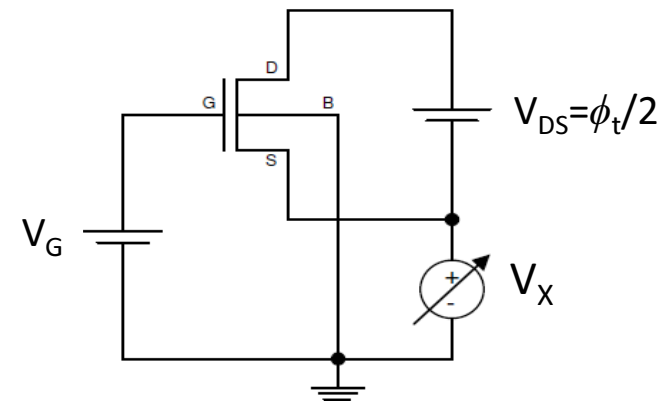
for $i_f = 3$ and
 $V_{DS} = \phi_t / 2$
 we have $i_r = 2.12$



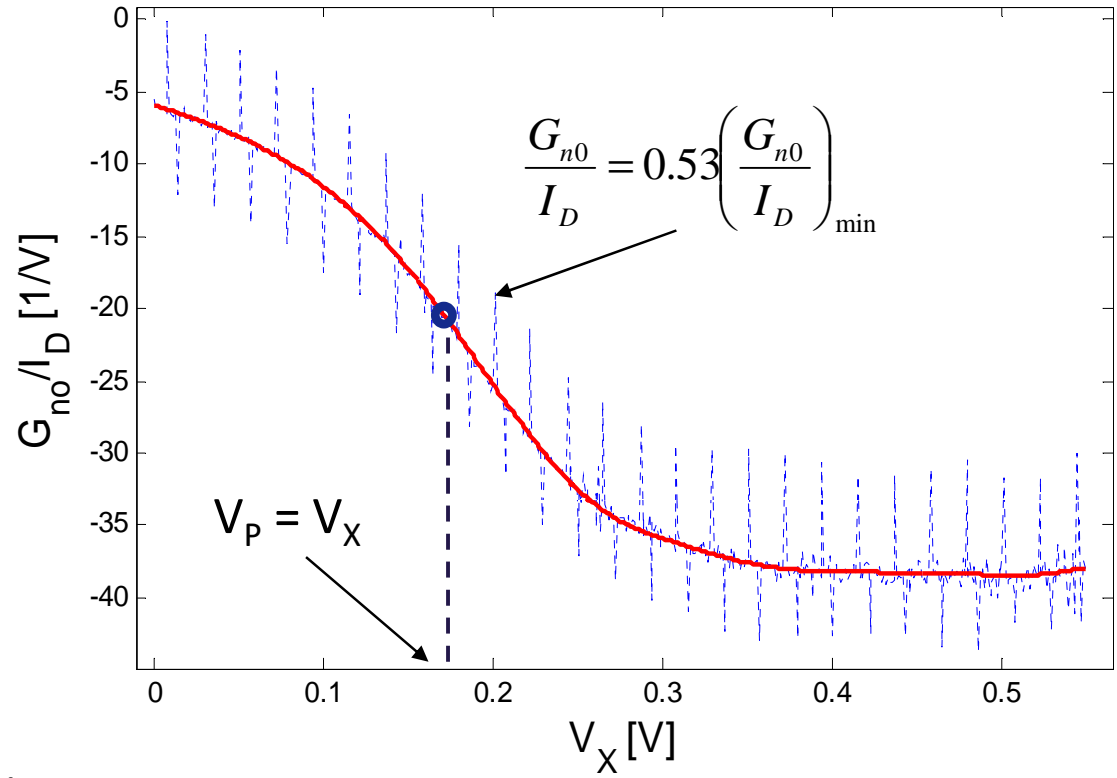
$$\frac{G_{n0}}{I_D} = 0.53 * \left(\frac{G_{n0}}{I_D} \right)_{\min}$$

and

$$V_P = V_X$$



The G_{n0}/I_D methodology – extract V_T and I_S



When

$$\frac{G_{n0}}{I_D} = 0.53 * \left(\frac{G_{n0}}{I_D} \right)_{\min}$$

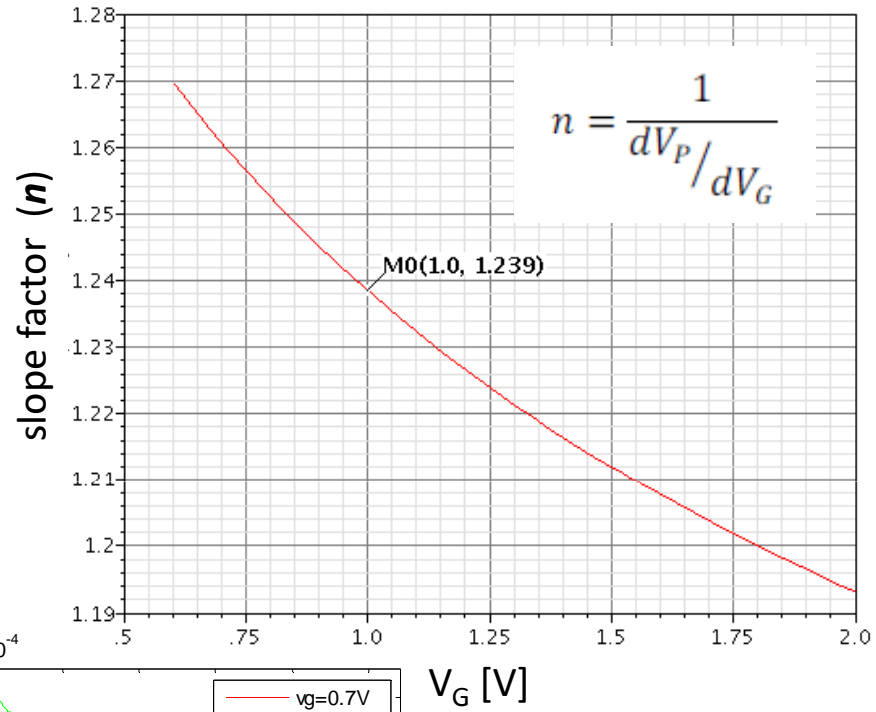
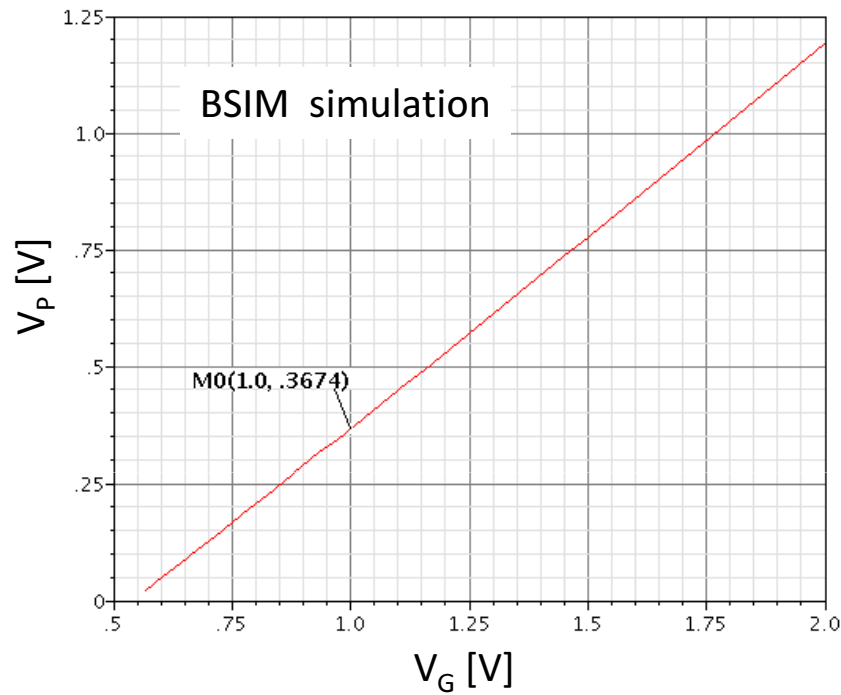


$$V_{T0} = -nV_P + V_G$$

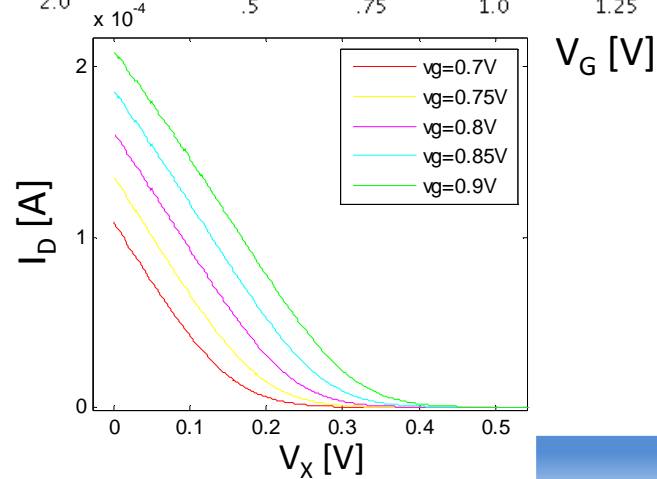
and

$$I_S = I_D$$

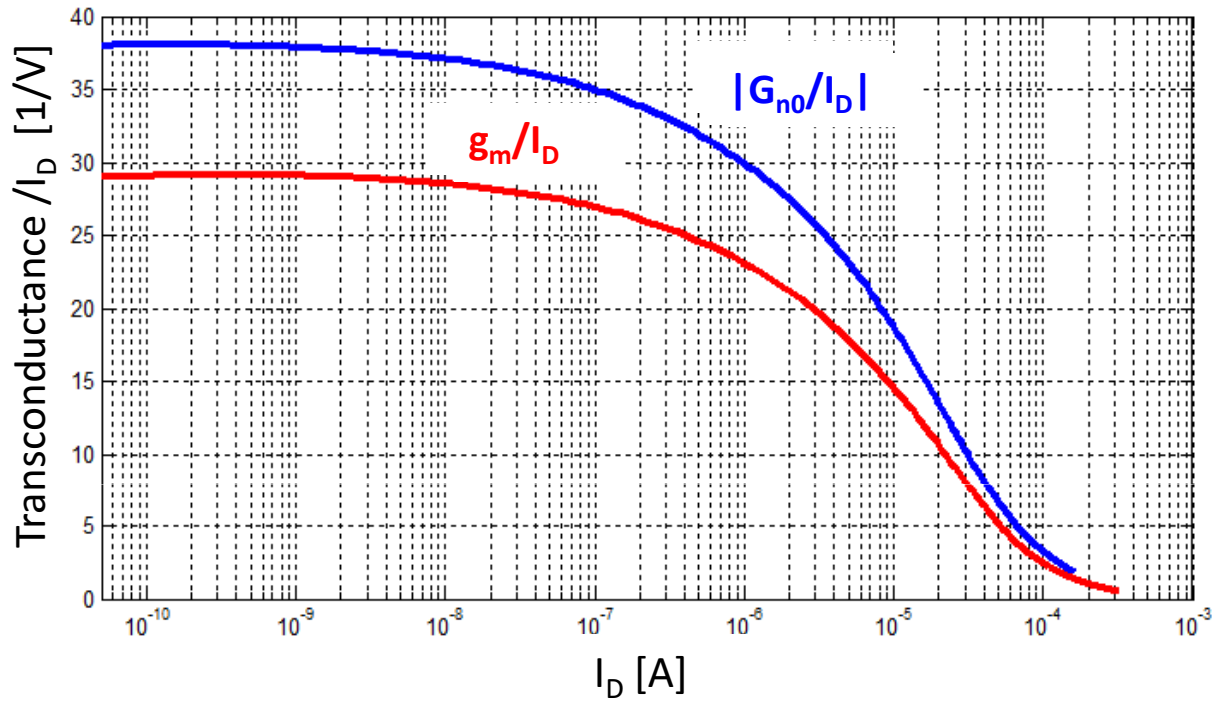
The G_{m0}/I_D methodology – extract pinch-off voltage V_P and slope factor n



measuring $I_D \times V_S$ for different V_G values



Gn0/Id x gm/Id methods



$$\frac{g_{m0}}{I_D} = \frac{2}{n\phi_t(\sqrt{1+i_f} + \sqrt{1+i_r})}$$

$$\frac{G_{n0}}{I_D} = \frac{-2}{\phi_t(\sqrt{1+i_f} + \sqrt{1+i_r})}$$

Gn0/Id x gm/Id methods

0.18 μm technology

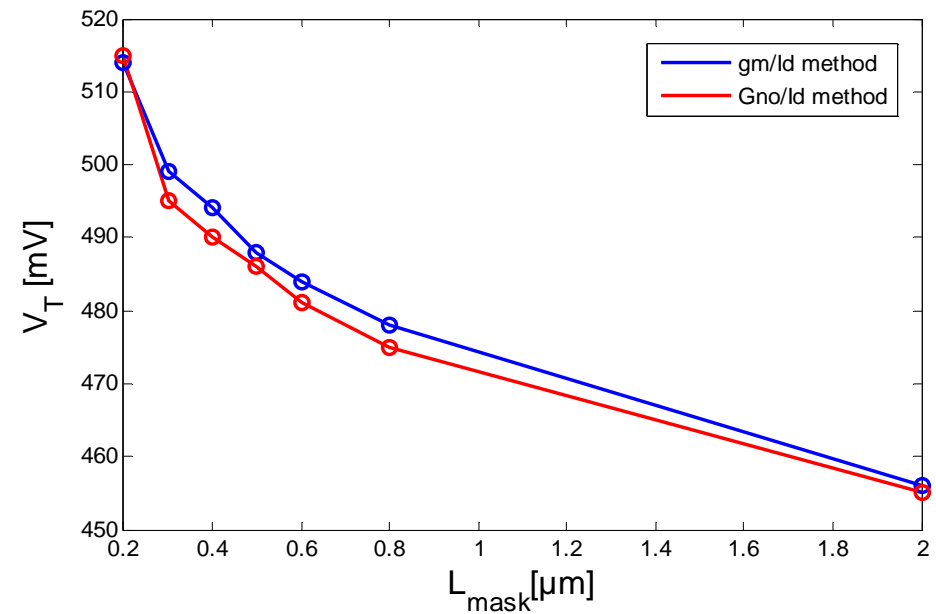
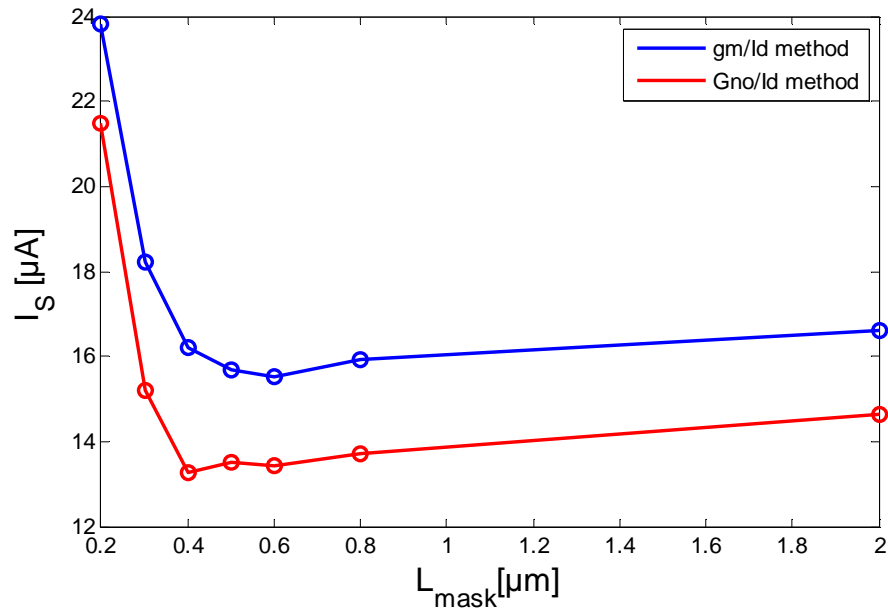
V_{T0}

L_{mask} (W/L=100)	0.2 μm	0.3 μm	0.4 μm	0.5 μm	0.6 μm	0.8 μm	2.0 μm
V_T (mV) gm/Id	514	499	494	488	484	478	456
V_T (mV) Gn0/Id	515	495	490	486	481	475	455

I_s

L_{mask} (W/L=100)	0.2 μm	0.3 μm	0.4 μm	0.5 μm	0.6 μm	0.8 μm	2.0 μm
I_s (μA) gm/Id	23.82	18.21	16.19	15.67	15.54	15.94	16.62
I_s (μA) Gn0/ID	21.47	15.21	13.27	13.53	13.41	13.72	14.65

I_s when $V_{GS} \approx V_{T0}$



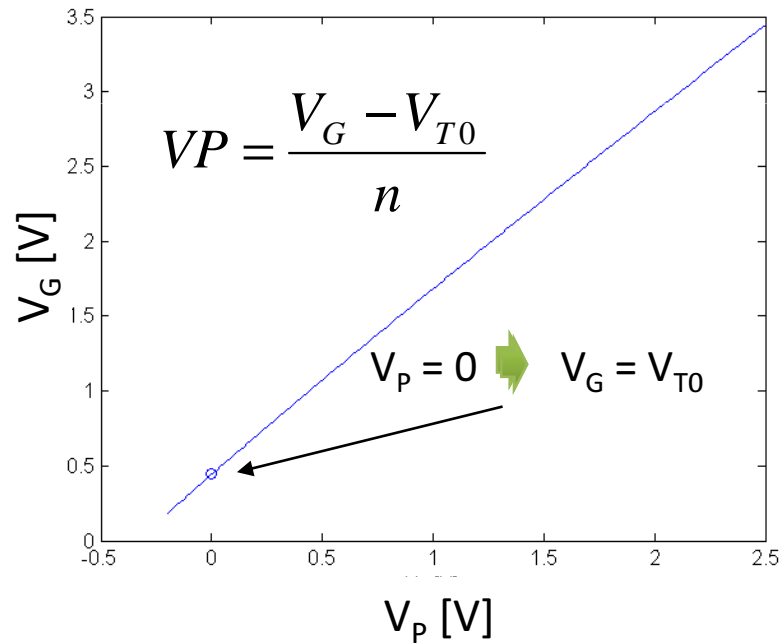
Applications

Applications using V_T extraction

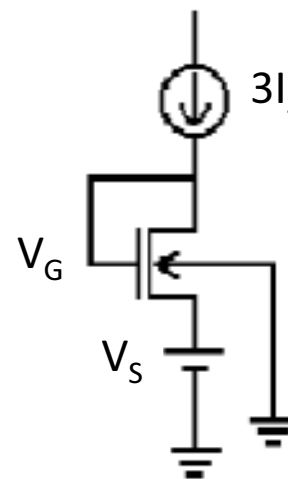
- Transistor aging (or electrical stress)
- Matching assessment
- Temperature drift characterization
- Radiations effects on MOS transistor

Applications

1- Extract I_S and V_T in a non-noisy environment using an accurate method (g_m/I_d or G_{n0}/I_d)



2- Extract V_T in a real environment considering $I_d = 3 \cdot I_S$ ($i_f = 3$) in a saturated transistor

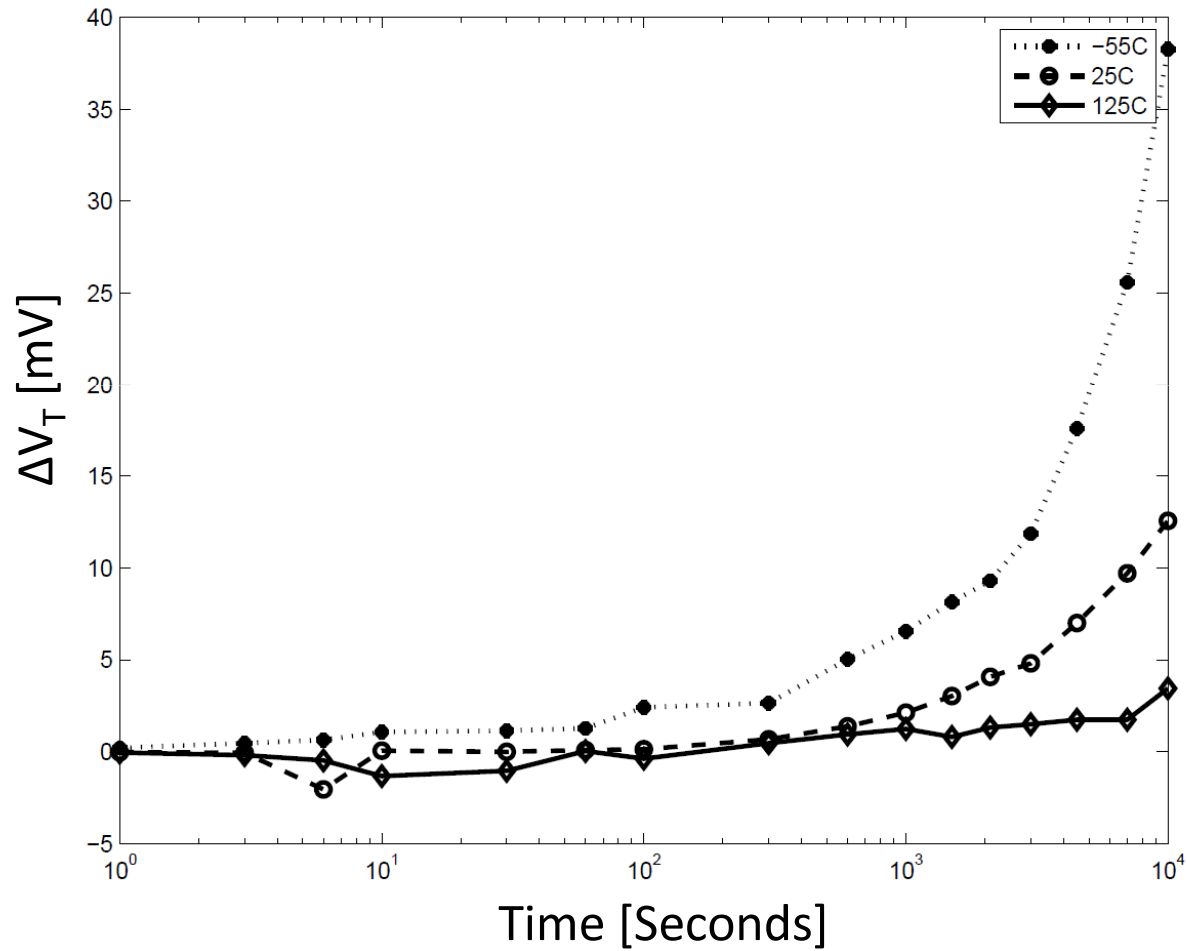


From UICM

when $i_f = 3$, $V_P = V_S$

Applications

Example of HCI stress measurement using V_T variation



Conclusions

- New procedure for direct determination of the threshold voltage and some other important electrical parameters with minimum influence of second order effects.
- The threshold voltage is determined at a constant gate-to-substrate voltage, at a low drain-to-source voltage and with transistor operation in the weak and moderate inversion regions.
- Under these operating conditions the effects of series resistances, mobility and slope factor variations, and channel length modulation are practically negligible, allowing a direct determination of the threshold voltage and of the DIBL effect.